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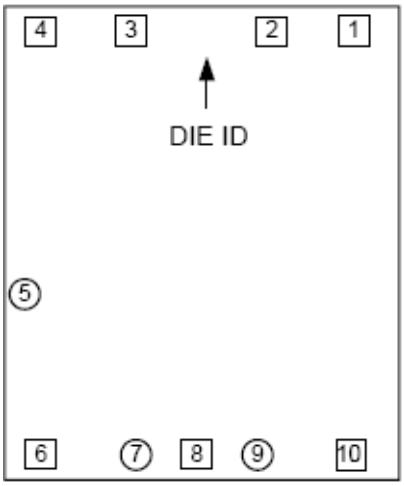
DPBU
Die Datasheet

LM95172QA2 MDA MCD2670A
13-BIT TO 16-BIT DIGITAL TEMPERATURE SENSOR WITH 3-WIRE INTERFACE

November 13,2008

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM95172A	Bond Pad Opening Size (min)	69µm x 69µm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1143µm x 1607µm 45.0mils x 63.3mils	Back Side Connection	GND
Thickness	254µm Nominal		
Min Pitch	255µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Vdd Analog	1	497.75	728.80	69	x	69
Vdd IO	2	242.80	728.80	69	x	69
$\overline{\text{OVERTEMP}}$	3	-147.35	728.80	69	x	69
SC	4	-497.75	728.80	69	x	69
NC	5	-	-	-	-	-
$\overline{\text{CS}}$	6	-497.75	-728.80	69	x	69
NC	7	-	-	-	-	-
GND	8	0.00	-728.80	69	x	69
NC	9	-	-	-	-	-
SI/O	10	497.65	-728.80	69	x	69

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Notes

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